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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	55
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	7.5K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f212bcsnfa-v2

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Table 1.4 Specifications for R8C/2B Group (2)

Item	Function	Specification
Serial Interface	UART0, UART1, UART2	Clock synchronous serial I/O/UART × 3
Clock Synchronous Serial I/O with Chip Select (SSU)		1 (shared with I ² C-bus)
I ² C bus ⁽¹⁾		1 (shared with SSU)
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function
D/A Converter		8-bit resolution × 2 circuits
Flash Memory		• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 3.0 to 5.5 V) f(XIN) = 10 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 2.2 to 5.5 V)
Current consumption		12 mA (VCC = 5.0 V, f(XIN) = 20 MHz) 5.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) 2.1 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) 0.65 μA (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		-20 to 85°C (N version) -40 to 85°C (D version) ⁽²⁾ -20 to 105°C (Y version) ⁽³⁾
Package		64-pin LQFP • Package code: PLQP0064KB-A (previous code: 64P6Q-A) • Package code: PLQP0064GA-A (previous code: 64P6U-A) 64-pin FLGA • Package code: PTLG0064JA-A (previous code: 64F0G)

NOTES:

1. I²C bus is a trademark of Koninklijke Philips Electronics N. V.
2. Specify the D version if D version functions are to be used.
3. Please contact Renesas Technology sales offices for the Y version.

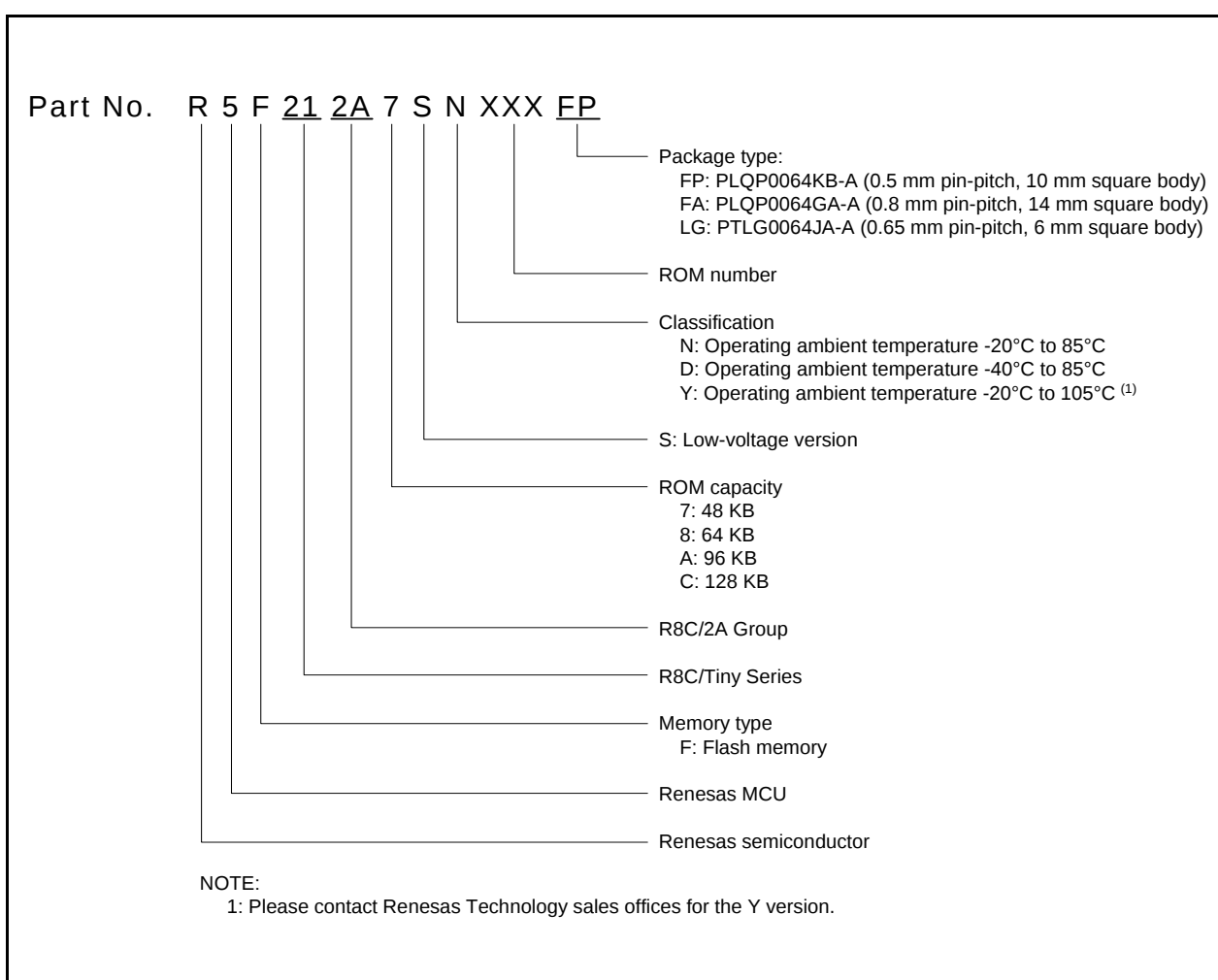


Figure 1.1 Part Number, Memory Size, and Package of R8C/2A Group

1.4 Pin Assignment

Figure 1.4 shows 64-pin LQFP Package Pin Assignment (Top View). Figure 1.5 shows 64-pin FLGA Package Pin Assignment (Top Perspective View). Tables 1.7 and 1.8 outlines the Pin Name Information by Pin Number.

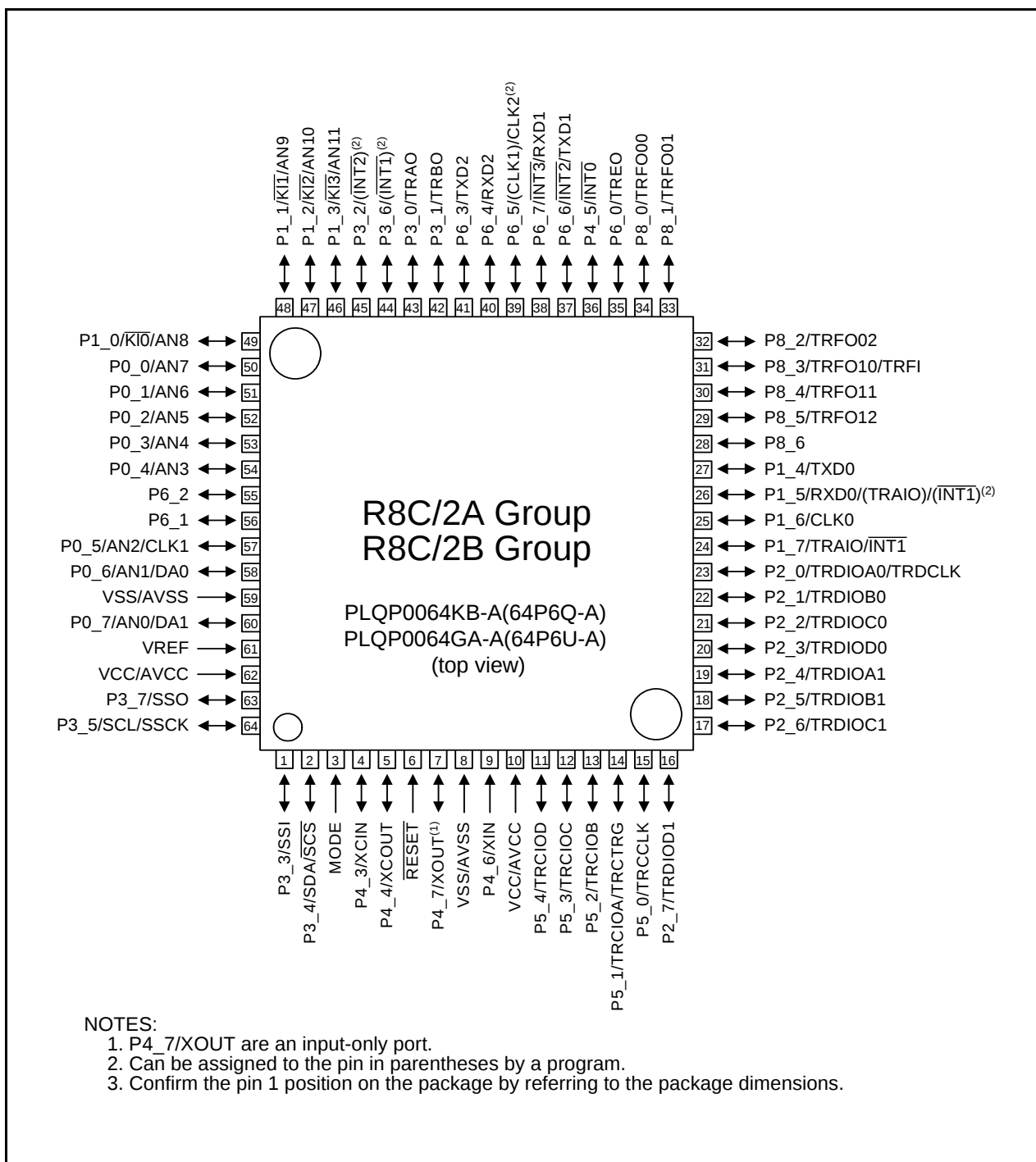


Figure 1.4 64-pin LQFP Package Pin Assignment (Top View)

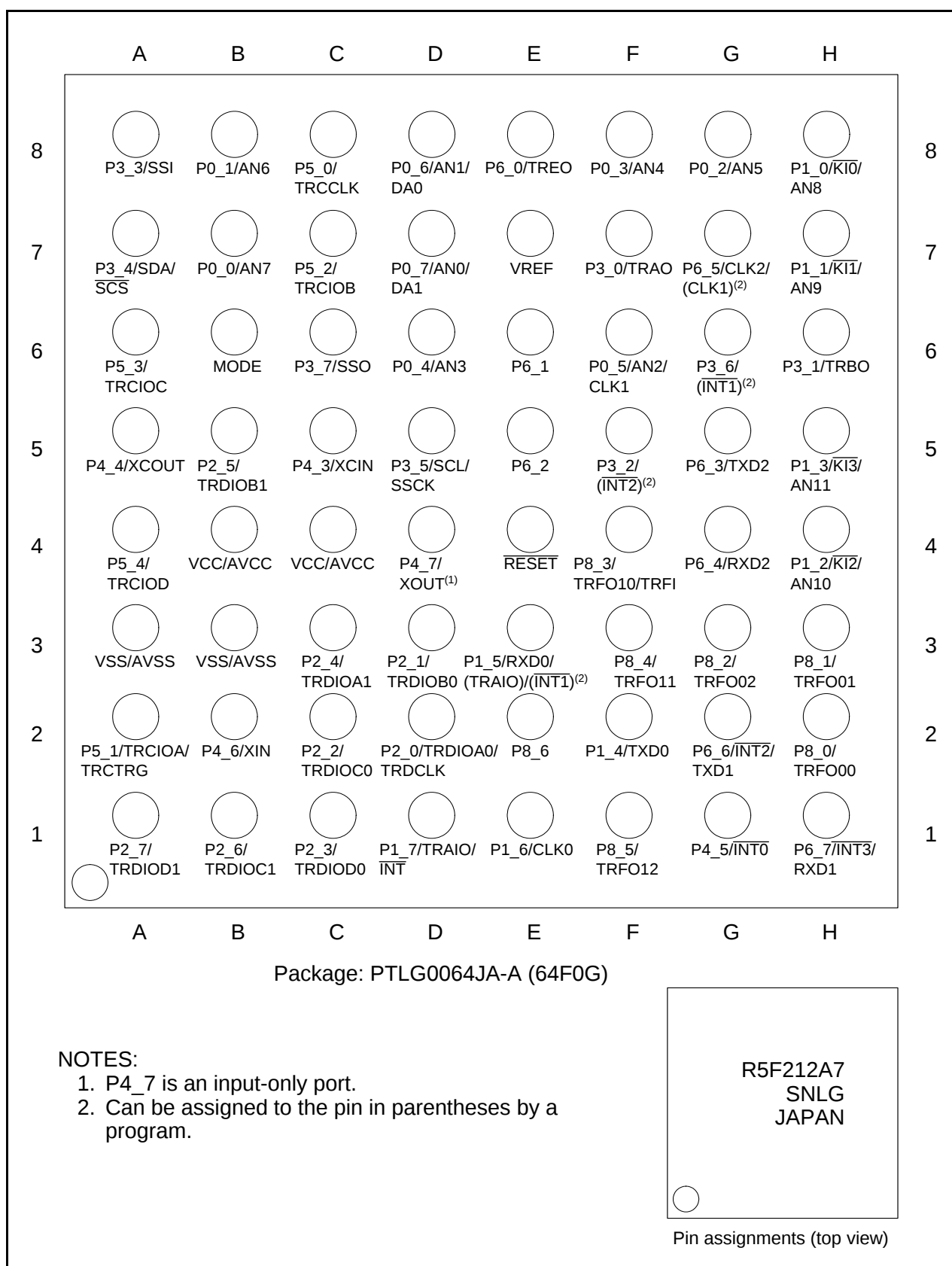


Figure 1.5 64-pin FLGA Package Pin Assignment (Top Perspective View)

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.

Interrupt are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.

The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

3.2 R8C/2B Group

Figure 3.2 is a Memory Map of R8C/2B Group. The R8C/2B group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal ROM (data flash) is allocated addresses 02400h to 02BFFh.

The internal RAM area is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

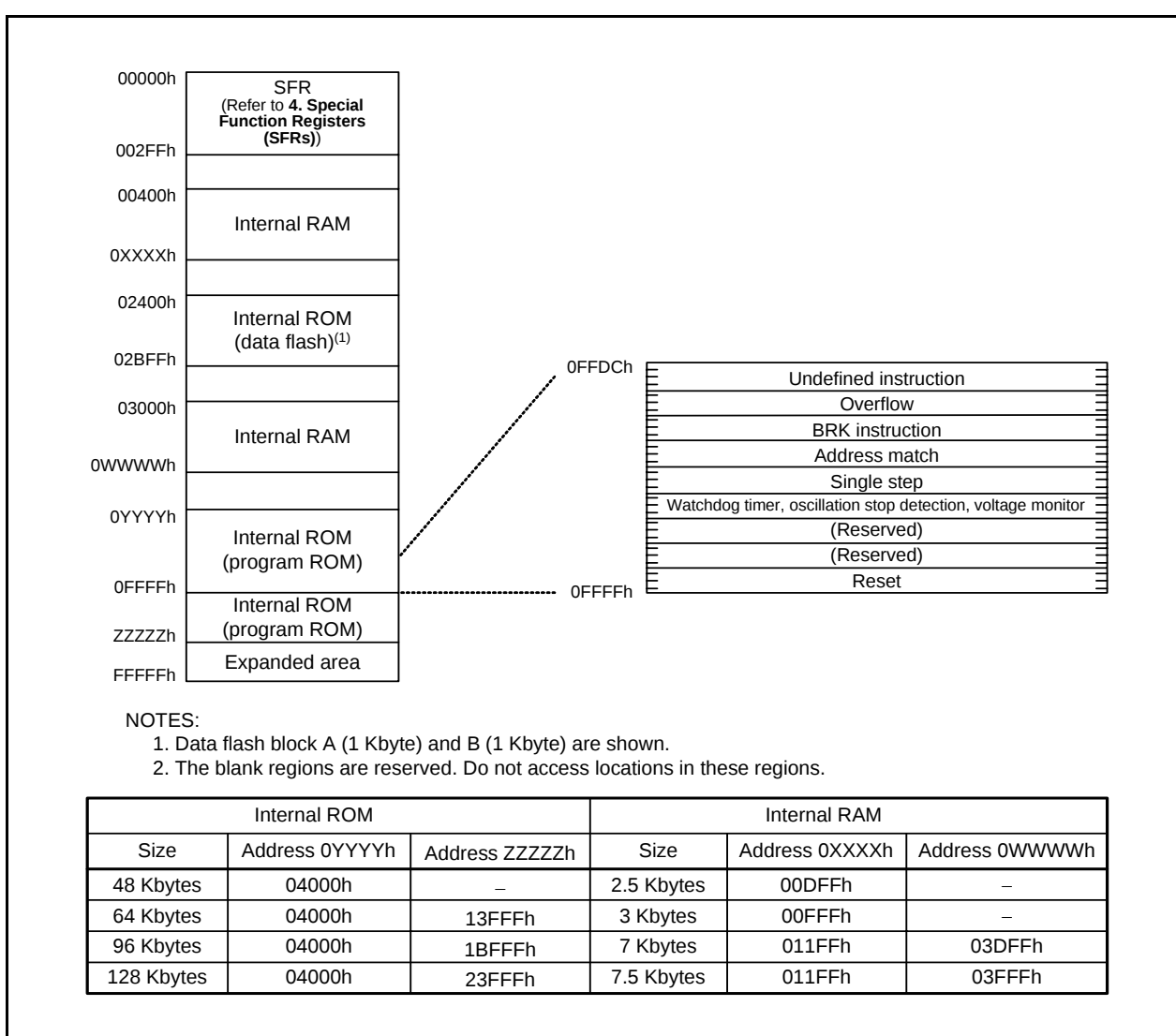


Figure 3.2 Memory Map of R8C/2B Group

Table 4.4 SFR Information (4)⁽¹⁾

Address	Register	Symbol	After reset
00C0h			
00C1h			
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h			
00D5h			
00D6h			
00D7h			
00D8h	D/A Register 0	DA0	00h
00D9h			
00DAh	D/A Register 1	DA1	00h
00DBh			
00DCh	D/A Control Register	DACON	00h
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h	Port P5 Register	P5	XXh
00EAh	Port P4 Direction Register	PD4	00h
00EBh	Port P5 Direction Register	PD5	00h
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h	Port P2 Drive Capacity Control Register	P2DRR	00h
00F5h	UART1 Function Select Register	U1SR	000000XXb
00F6h			
00F7h			
00F8h	Port Mode Register	PMR	00h
00F9h	External Input Enable Register	INTEN	00h
00FAh	INT Input Filter Select Register	INTF	00h
00FBh	Key Input Enable Register	KIEN	00h
00FCh	Pull-Up Control Register 0	PUR0	00h
00FDh	Pull-Up Control Register 1	PUR1	XX000000b
00FEh			
00FFh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.5 SFR Information (5)⁽¹⁾

Address	Register	Symbol	After reset
0100h	Timer RA Control Register	TRACR	00h
0101h	Timer RA I/O Control Register	TRAIOC	00h
0102h	Timer RA Mode Register	TRAMR	00h
0103h	Timer RA Prescaler Register	TRAPRE	FFh
0104h	Timer RA Register	TRA	FFh
0105h	LIN Control Register 2	LINCR2	00h
0106h	LIN Control Register	LINCR	00h
0107h	LIN Status Register	LINST	00h
0108h	Timer RB Control Register	TRBCR	00h
0109h	Timer RB One-Shot Control Register	TRBOCR	00h
010Ah	Timer RB I/O Control Register	TRBIOC	00h
010Bh	Timer RB Mode Register	TRBMR	00h
010Ch	Timer RB Prescaler Register	TRBPRES	FFh
010Dh	Timer RB Secondary Register	TRBSC	FFh
010Eh	Timer RB Primary Register	TRBPR	FFh
010Fh			
0110h			
0111h			
0112h			
0113h			
0114h			
0115h			
0116h			
0117h			
0118h	Timer RE Second Data Register / Counter Data Register	TRESEC	00h
0119h	Timer RE Minute Data Register / Compare Data Register	TREMIN	00h
011Ah	Timer RE Hour Data Register	TREHR	00h
011Bh	Timer RE Day of Week Data Register	TREWK	00h
011Ch	Timer RE Control Register 1	TRECR1	00h
011Dh	Timer RE Control Register 2	TRECR2	00h
011Eh	Timer RE Clock Source Select Register	TRECSR	00001000b
011Fh			
0120h	Timer RC Mode Register	TRCMR	01001000b
0121h	Timer RC Control Register 1	TRCCR1	00h
0122h	Timer RC Interrupt Enable Register	TRCIER	01110000b
0123h	Timer RC Status Register	TRCSR	01110000b
0124h	Timer RC I/O Control Register 0	TRCIOR0	10001000b
0125h	Timer RC I/O Control Register 1	TRCIOR1	10001000b
0126h	Timer RC Counter	TRC	00h
0127h			00h
0128h	Timer RC General Register A	TRCGRA	FFh
0129h			FFh
012Ah	Timer RC General Register B	TRCGRB	FFh
012Bh			FFh
012Ch	Timer RC General Register C	TRCGRC	FFh
012Dh			FFh
012Eh	Timer RC General Register D	TRCGRD	FFh
012Fh			FFh
0130h	Timer RC Control Register 2	TRCCR2	00011111b
0131h	Timer RC Digital Filter Function Select Register	TRCDF	00h
0132h	Timer RC Output Master Enable Register	TRCOER	01111111b
0133h			
0134h			
0135h			
0136h			
0137h	Timer RD Start Register	TRDSTR	11111100b
0138h	Timer RD Mode Register	TRDMR	00001110b
0139h	Timer RD PWM Mode Register	TRDPMR	10001000b
013Ah	Timer RD Function Control Register	TRDFCR	10000000b
013Bh	Timer RD Output Master Enable Register 1	TRDOER1	FFh
013Ch	Timer RD Output Master Enable Register 2	TRDOER2	01111111b
013Dh	Timer RD Output Control Register	TRDOCR	00h
013Eh	Timer RD Digital Filter Function Select Register 0	TRDDF0	00h
013Fh	Timer RD Digital Filter Function Select Register 1	TRDDF1	00h

NOTE:

1. The blank regions are reserved. Do not access locations in these regions

Table 4.6 SFR Information (6)⁽¹⁾

Address	Register	Symbol	After reset
0140h	Timer RD Control Register 0	TRDCR0	00h
0141h	Timer RD I/O Control Register A0	TRDIOA0	10001000b
0142h	Timer RD I/O Control Register C0	TRDIORC0	10001000b
0143h	Timer RD Status Register 0	TRDSR0	11000000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIOA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h			FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh			FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh			FFh
0160h	UART2 Transmit/Receive Mode Register	U2MR	00h
0161h	UART2 Bit Rate Register	U2BRG	XXh
0162h	UART2 Transmit Buffer Register	U2TB	XXh
0163h			XXh
0164h	UART2 Transmit/Receive Control Register 0	U2C0	00001000b
0165h	UART2 Transmit/Receive Control Register 1	U2C1	00000010b
0166h	UART2 Receive Buffer Register	U2RB	XXh
0167h			XXh
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h			
0171h			
0172h			
0173h			
0174h			
0175h			
0176h			
0177h			
0178h			
0179h			
017Ah			
017Bh			
017Ch			
017Dh			
017Eh			
017Fh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.7 SFR Information (7)(1)

Address	Register	Symbol	After reset
0180h			
0181h			
0182h			
0183h			
0184h			
0185h			
0186h			
0187h			
0188h			
0189h			
018Ah			
018Bh			
018Ch			
018Dh			
018Eh			
018Fh			
0190h			
0191h			
0192h			
0193h			
0194h			
0195h			
0196h			
0197h			
0198h			
0199h			
019Ah			
019Bh			
019Ch			
019Dh			
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h			
01B3h	Flash Memory Control Register 4	FMR4	01000000b
01B4h			
01B5h	Flash Memory Control Register 1	FMR1	1000000Xb
01B6h			
01B7h	Flash Memory Control Register 0	FMR0	00000001b
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.11 SFR Information (11)⁽¹⁾

Address	Register	Symbol	After reset
0280h			
0281h			
0282h			
0283h			
0284h			
0285h			
0286h			
0287h			
0288h			
0289h			
028Ah			
028Bh			
028Ch			
028Dh			
028Eh			
028Fh			
0290h	Timer RF Register	TRF	00h
0291h			00h
0292h			
0293h			
0294h			
0295h			
0296h			
0297h			
0298h			
0299h			
029Ah	Timer RF Control Register 0	TRFCR0	00h
029Bh	Timer RF Control Register 1	TRFCR1	00h
029Ch	Capture / Compare 0 Register	TRFM0	0000h ⁽²⁾
029Dh			FFFFh ⁽³⁾
029Eh	Compare 1 Register	TRFM1	FFh
029Fh			FFh
02A0h			
02A1h			
02A2h			
02A3h			
02A4h			
02A5h			
02A6h			
02A7h			
02A8h			
02A9h			
02AAh			
02ABh			
02ACh			
02ADh			
02AEh			
02AFh			
02B0h			
02B1h			
02B2h			
02B3h			
02B4h			
02B5h			
02B6h			
02B7h			
02B8h			
02B9h			
02BAh			
02BBh			
02BCh			
02BDh			
02BEh			
02BFh			

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. After input capture mode.
3. After output compare mode.

5. Electrical Characteristics

The electrical characteristics of N version ($T_{opr} = -20^{\circ}\text{C}$ to 85°C) and D version ($T_{opr} = -40^{\circ}\text{C}$ to 85°C) are listed below.

Please contact Renesas Technology sales offices for the electrical characteristics in the Y version ($T_{opr} = -20^{\circ}\text{C}$ to 105°C).

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V_{CC}/AV_{CC}	Supply voltage		-0.3 to 6.5	V
V_I	Input voltage		-0.3 to $V_{CC} + 0.3$	V
V_O	Output voltage		-0.3 to $V_{CC} + 0.3$	V
P_d	Power dissipation	$T_{opr} = 25^{\circ}\text{C}$	700	mW
T_{opr}	Operating ambient temperature		-20 to 85 (N version) / -40 to 85 (D version)	$^{\circ}\text{C}$
T_{stg}	Storage temperature		-65 to 150	$^{\circ}\text{C}$

Table 5.14 Timing Requirements of Clock Synchronous Serial I/O with Chip Select⁽¹⁾

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	–	–	tcyc ⁽²⁾
t _{HI}	SSCK clock "H" width			0.4	–	0.6	tsucyc
t _{LO}	SSCK clock "L" width			0.4	–	0.6	tsucyc
trise	SSCK clock rising time	Master		–	–	1	tcyc ⁽²⁾
		Slave		–	–	1	μs
tfall	SSCK clock falling time	Master		–	–	1	tcyc ⁽²⁾
		Slave		–	–	1	μs
tsu	SSO, SSI data input setup time			100	–	–	ns
t _H	SSO, SSI data input hold time			1	–	–	tcyc ⁽²⁾
t _{LEAD}	$\overline{\text{SCS}}$ setup time	Slave		1tcyc + 50	–	–	ns
t _{LAG}	$\overline{\text{SCS}}$ hold time	Slave		1tcyc + 50	–	–	ns
t _{OD}	SSO, SSI data output delay time			–	–	1	tcyc ⁽²⁾
t _{SA}	SSI slave access time		2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	1.5tcyc + 100	ns
			2.2 V ≤ V _{CC} < 2.7 V	–	–	1.5tcyc + 200	ns
t _{OR}	SSI slave out open time		2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	1.5tcyc + 100	ns
			2.2 V ≤ V _{CC} < 2.7 V	–	–	1.5tcyc + 200	ns

NOTES:

1. V_{CC} = 2.2 to 5.5 V, V_{SS} = 0 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. 1tcyc = 1/f₁(s)

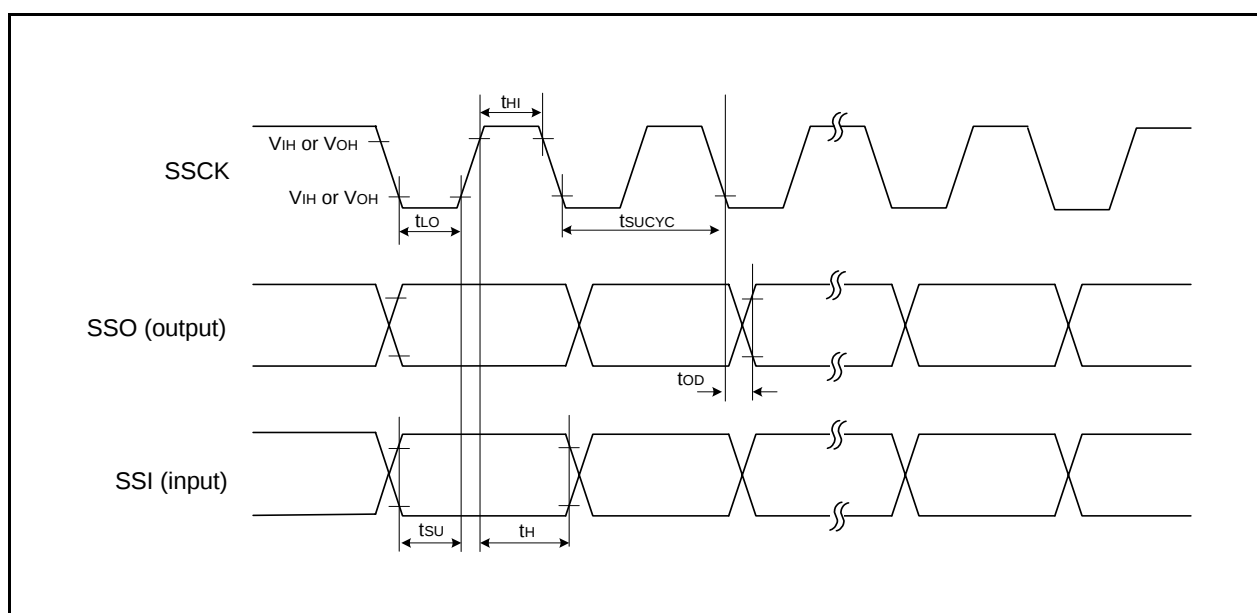


Figure 5.6 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Clock Synchronous Communication Mode)

Table 5.16 Electrical Characteristics (1) [V_{CC} = 5 V]

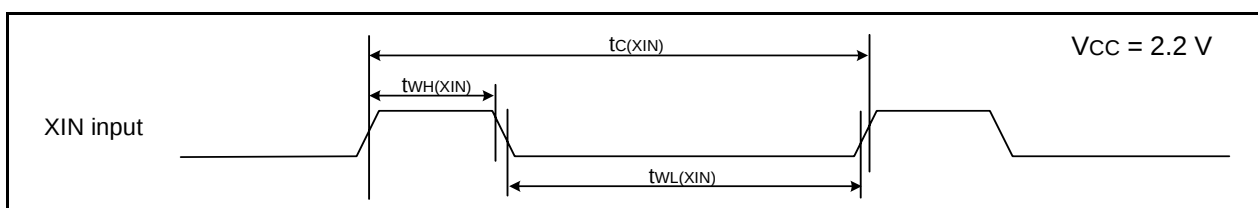
Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except P2_0 to P2_7, XOUT	I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
			I _{OH} = -200 μA	V _{CC} - 0.5	—	V _{CC}	V
		P2_0 to P2_7	Drive capacity HIGH I _{OH} = -20 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity LOW I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
		XOUT	Drive capacity HIGH I _{OH} = -1 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity LOW I _{OH} = -500 μA	V _{CC} - 2.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except P2_0 to P2_7, XOUT	I _{OL} = 5 mA	—	—	2.0	V
			I _{OL} = 200 μA	—	—	0.45	V
		P2_0 to P2_7	Drive capacity HIGH I _{OL} = 20 mA	—	—	2.0	V
			Drive capacity LOW I _{OL} = 5 mA	—	—	2.0	V
		XOUT	Drive capacity HIGH I _{OL} = 1 mA	—	—	2.0	V
			Drive capacity LOW I _{OL} = 500 μA	—	—	2.0	V
V _{T+} -V _{T-}	Hysteresis	<u>INT0</u> , <u>INT1</u> , <u>INT2</u> , <u>INT3</u> , <u>KI0</u> , <u>KI1</u> , <u>KI2</u> , <u>KI3</u> , <u>TRAIO</u> , <u>TRFI</u> , <u>RXD0</u> , <u>RXD1</u> , <u>CLK0</u> , <u>CLK1</u> , <u>CLK2</u> , <u>SSI</u> , <u>SCL</u> , <u>SDA</u> , <u>SSO</u>		0.1	0.5	—	V
		<u>RESET</u>		0.1	1.0	—	V
I _{IH}	Input "H" current		V _I = 5 V	—	—	5.0	μA
I _{IL}	Input "L" current		V _I = 0 V	—	—	-5.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V	30	50	167	kΩ
R _{FXIN}	Feedback resistance	XIN		—	1.0	—	MΩ
R _{FXCIN}	Feedback resistance	XCIN		—	18	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode	1.8	—	—	V

NOTE:

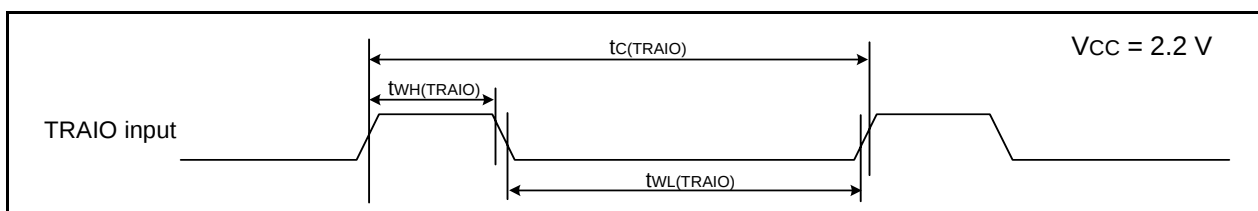
- V_{CC} = 4.2 to 5.5 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 2.2\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^\circ\text{C}$) [$V_{CC} = 2.2\text{ V}$]****Table 5.32 XIN Input, XCIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	200	–	ns
$t_{WH(XIN)}$	XIN input “H” width	90	–	ns
$t_{WL(XIN)}$	XIN input “L” width	90	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

**Figure 5.18 XIN Input and XCIN Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.33 TRAIO Input, $\overline{\text{INT1}}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	TBD	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	TBD	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	TBD	–	ns

**Figure 5.19 TRAIO Input and $\overline{\text{INT1}}$ Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.34 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	2000 ⁽¹⁾	–	ns
$t_{WH(TRFI)}$	TRFI input “H” width	1000 ⁽²⁾	–	ns
$t_{WL(TRFI)}$	TRFI input “L” width	1000 ⁽²⁾	–	ns

NOTES:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

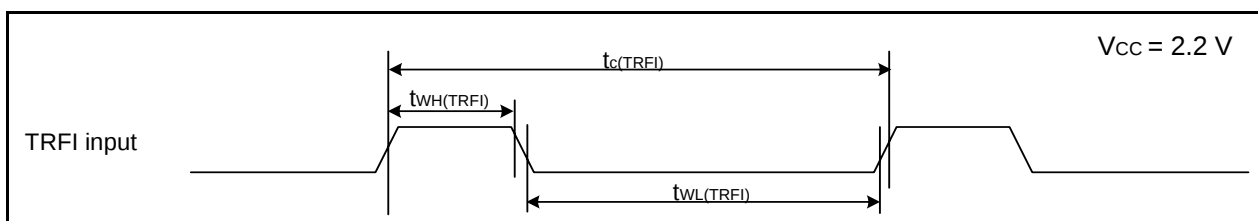
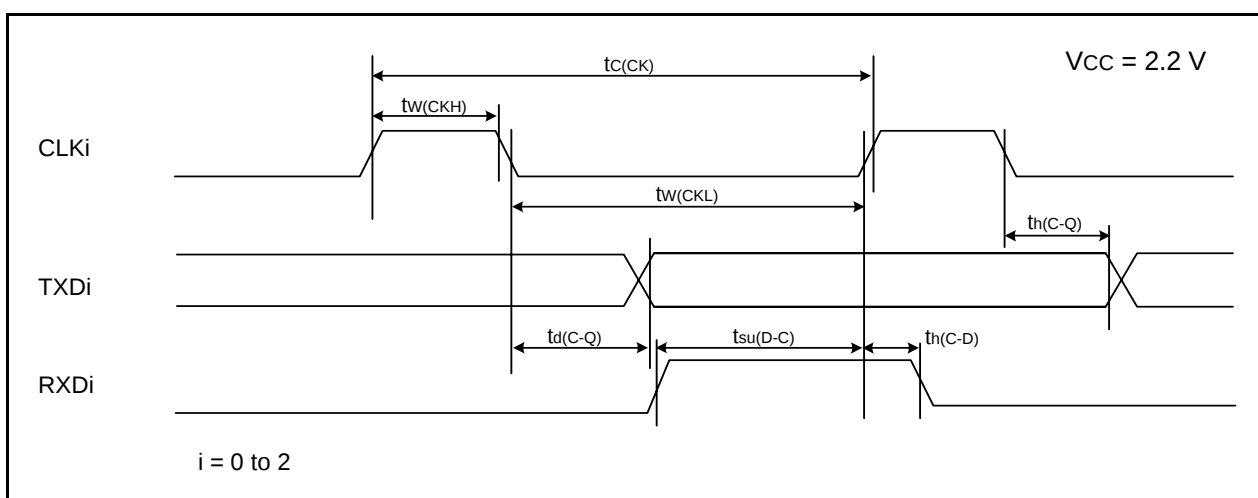
**Figure 5.20 TRFI Input Timing Diagram when $V_{CC} = 2.2\text{ V}$**

Table 5.35 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800	—	ns
$t_{w(CKH)}$	CLKi input "H" width	400	—	ns
$t_{w(CKL)}$	CLKi input "L" width	400	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	200	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	150	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

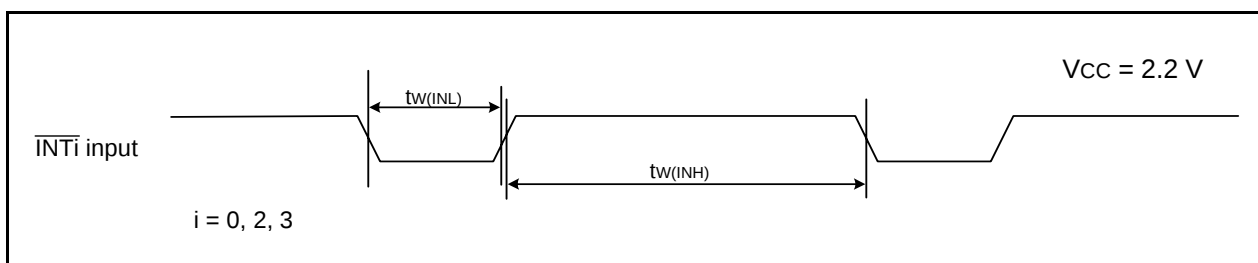
i = 0 to 2

**Figure 5.21 Serial Interface Timing Diagram when Vcc = 2.2 V****Table 5.36 External Interrupt $\overline{INTi}$ (i = 0, 2, 3) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	1000 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	1000 ⁽²⁾	—	ns

NOTES:

1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency $\times$ 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency $\times$ 3) or the minimum value of standard, whichever is greater.

**Figure 5.22 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 2.2 V**

REVISION HISTORY	R8C/2A Group, R8C/2B Group Datasheet
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Rev.	Date	Description	
		Page	Summary
0.30	Dec 22, 2006	19	Table 4.1; • 000Ah: "00XX000b" → "00h" revised • 0008h: "Module Standby Control Register" → "Module Operation Enable Register" revised • 000Fh: "0001111b" → "00X1111b" revised
		37	Table 5.11 revised
1.00	Feb 09, 2007	All pages	"Preliminary" deleted
		3	Table 1.2 revised
		5	Table 1.4 revised
		6	Table 1.5 and Figure 1.1 revised
		7	Table 1.6 and Figure 1.2 revised
		17	Figure 3.1 revised
		18	Figure 3.2 revised
		19	Table 4.1; • 0008h: "Module Standby Control Register" → "Module Operation Enable Register" revised • 000Ah: "00XX000b" → "00h" revised • 000Fh: "0001111b" → "00X1111b" revised • 002Bh: "High-Speed On-Chip Oscillator Control Register 6" added
		23	Table 4.5; 0105h: "LIN Control Register 2" register name revised
		31	Table 5.2 revised
		32	Table 5.3 and Table 5.4; NOTE1 revised
		37	Table 5.11 revised
		44	Table 5.17 revised
		46	Table 5.21 and Figure 5.11; "i = 0 to 2" revised
		48	Table 5.24 revised
		50	Table 5.28 revised, Figure 5.16 "i = 0 to 2" revised
		52	Table 5.31 revised
		53	Table 5.34 revised
		54	Table 5.35 and Figure 5.21; "i = 0 to 2" revised
2.00	Oct 17, 2007	All pages	"PTLG0064JA-A (64F0G) package" added
		3, 5	Table 1.2 and Table 1.4; • Operating Ambient Temperature: Y version added • Package: 64-pin FLGA added
		6 to 7	Table 1.5 and Figure 1.1 revised
		8	Table 1.6 and Figure 1.2 revised
		10	Figure 1.4 "64-pin LQFP Package" added
		11	Figure 1.5 added
		19 to 20	Figure 3.1 and Figure 3.2 revised
		24	Table 4.4; 00F5h: "00h" → "000000XXb" revised

Notes:

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